

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A method comprising:

directing first energy to only a first interconnect element, the first interconnect element contacting a first conductive contact of a first device and a second conductive contact of a second device, the first interconnect element to form a first electrical connection between the first conductive contact and the second conductive contact based at least in part on the first energy; and

after directing the first energy to only the first interconnect element, directing second energy to only a second interconnect element, the second interconnect element contacting a third conductive contact of the first device and a fourth conductive contact of the second device, the second interconnect element to form a second electrical connection between the third conductive contact and the fourth conductive contact based at least in part on the second energy.

2. (original) A method according to Claim 1, wherein directing the first energy comprises directing a laser at the first interconnect element, and

wherein directing the second energy comprises directing the laser at the second interconnect element.

3. (original) A method according to Claim 1, wherein the first interconnect element comprises a Controlled Collapse Chip Connect interconnect element.

4. (original) A method according to Claim 1, wherein the first interconnect element comprises a solder ball.

5. (original) A method according to Claim 1, wherein at least one of the first conductive contact, the second conductive contact, the third conductive contact, and the fourth conductive contact comprise solder paste.

6. (original) A method according to Claim 1, wherein the first conductive contact and the third conductive contact are disposed on an integrated circuit die, and

wherein the second conductive contact and the fourth conductive contact are disposed on an integrated circuit package.

7. (original) A method according to Claim 1, wherein the first conductive contact and the third conductive contact are disposed on an integrated circuit package, and

wherein the second conductive contact and the fourth conductive contact are disposed on a package interposer.

8. (original) A method according to Claim 1, further comprising:

joining the first device and the second device to create a combined device,

wherein a plurality of interconnect elements are disposed between the first device and the second device, and

wherein each of the plurality of interconnect elements is visible from one or more locations external to the combined device.

9. (cancelled)

10. (cancelled)

11. (cancelled)

12. (cancelled)

13. (cancelled)

14. (cancelled)

15. (cancelled)

16. (cancelled)

17. (cancelled)

18. (cancelled)

19. (newly added) A method to create a system including an integrated circuit die having a first plurality of conductive contacts, an integrated circuit package having a second plurality of conductive contacts, and a plurality of interconnect elements in contact with respective ones of the first plurality of conductive contacts and respective ones of the second plurality of conductive contacts, the method comprising:

directing first energy to only a first one of the plurality of interconnect elements, the first interconnect element contacting a first one of the first plurality of conductive contacts and a first one of the second plurality of conductive contacts, the first interconnect element to form a first electrical connection between the first one of the first plurality of conductive contacts and the first one of the second plurality of conductive contacts based at least in part on the first energy;

after directing the first energy to only the first interconnect element, directing second energy to only a second one of the plurality of interconnect elements, the second interconnect

element contacting a second one of the first plurality of conductive contacts and a second one of the second plurality of conductive contacts, the second interconnect element to form a second electrical connection between the second one of the first plurality of conductive contacts and the second one of the second plurality of conductive contacts based at least in part on the second energy; and

coupling a double data rate memory to the integrated circuit package

20. (newly added) A method according to Claim 19, wherein directing the first energy comprises directing a laser at the first interconnect element, and

wherein directing the second energy comprises directing the laser at the second interconnect element.

21. (newly added) A method according to Claim 19, wherein the first interconnect element comprises a Controlled Collapse Chip Connect interconnect element.

22. (newly added) A method according to Claim 19, wherein the first interconnect element comprises a solder ball.

23. (newly added) A method according to Claim 19, wherein at least one of the first conductive contact, the second conductive contact, the third conductive contact, and the fourth conductive contact comprise solder paste.

24. (newly added) A method according to Claim 19,
wherein each of the plurality of interconnect elements is visible from one or more locations external to the combined device.